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(21) International Application Number: PCT/US96/13443 (22) International Filing Date: 20 August 1996 (20.08.96) (30) Priority Data: 08/517,578 21 August 1995 (21.08.95) US (71) Applicant: RODEL, INC. [US/US]; 451 Bellevue Road, Newark, DE 19713 (US). (72) Inventor: ROBERTS, John, V., H.; 17 West Country Lane, Newark, DE 19702 (US). (74) Agent: BENSON, Kenneth, A.; P.O. Box 191, Chatham, PA 19318 (US).		(81) Designated States: CN, JP, KR, SG, European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE). Published <i>With international search report. Before the expiration of the time limit for amending the claims and to be republished in the event of the receipt of amendments.</i>
(54) Title: POLISHING PADS (57) Abstract A pad is provided for use on a machine for the polishing of silicon wafers which allows the use of optical detection of the wafer surface condition as the wafer is being polished. This is accomplished by constructing the entire pad or a portion thereof out of a solid uniform polymer sheet with no intrinsic ability to absorb or transport slurry particles and which is transparent to the light beam being used to detect the wafer surface condition by optical methods. Polymers which are transparent to light having a wavelength within the range of 190 to 3500 nanometers are suitable for the construction of these pads.		